

AMENDMENT UNDER 37 C.F.R. § 1.111
U.S. Appl. No. 09/974,048

B2
5. (Twice Amended) A connection structure for connecting a terminal portion of a circuit board with an external terminal formed in an external circuit, wherein said terminal portion is provided with a nickel plating layer and a soldering bump provided on said terminal portion and a thickness of said nickel plating layer is within a range of 1.0 to 4.0 μm , and

wherein said terminal portion is further provided with a base layer and a conductive layer, which is disposed between said base layer and said nickel plating layer, and wherein said base layer comprises polyimide resin.

Please add the following new claims 6-9:

ADD B3
6. (New) The circuit board according to claim 1, wherein a thickness of the base layer is 2-30 μm .

7. (New) The circuit board according to claim 1, wherein a thickness of the conductive layer is 3-25 μm .

8. (New) The circuit board according to claim 1, wherein the terminal portion further includes a cover layer disposed on said base layer, having a thickness of .5 - 8.0 μm .

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Cond B3
9. (New) The circuit board according to claim 3, wherein a composition ratio of said soldering bump is 95-97% by weight of said tin, 0-4% by weight of said silver, and 0-4% by weight of said copper.
